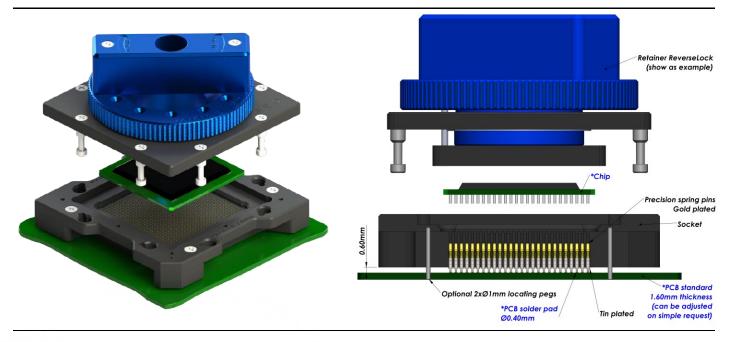
Standard SMT soldering Test Socket

For CGA / PGA / PGI Package

0.80 mm pitch (from 0.80 mm up to 0.99 mm)





E-tec Interconnect AG is the world leading Test socket manufacturer

The SMT socket uses the same footprint as your chip. Socket is simply placed and reflowed onto the PCB in the same way as the chip and it only requires a small amount of additional board space. SMT type sockets are available with all retention systems. We aim to solve your requirements. Please note, we will always request the chip data to ensure we offer a compatible socket. For SMT sockets in general, E-tec Interconnect AG recommends the use of locating pegs, which can be soldered to the PCB for added mechanical strength.

Specifications contact type code 0830			
Application	Surface mouting	Force	30 gr
Mounting	SMT	Current rating	1.8 A
Bandwidth (GHz@-1dB)	2.6(4.4) GHz	Capacitance pF	0.59 pF
Contact resistance	<100mOhm	Inductance nH	1.70 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	SMT	Mating cycles	100 K

cifications

How to order

CU # #### -0830 - # # # # # # 95 Shape of tip Nbr of **Contact type Plating** Option code (see page 16-19) contacts U: Concave 30 : Standard SMT - Dimension A = 0.60 mm 95 : Tin / Gold D: Dead bug Depends on Options: Other on request M: Multi frames ballcount of chip P: Pointed U: Multi packages C: Converter plate S: Custom opening slot Retention frame type (Lid) (see page 12-15) Grid code / Config. code L: Locating pegs W: TwistLock S: ScrewLock H: Heatsink Will be given by the F:FastLock Q: Open QuickLock (<200 contacts) F: Fan + Heatsink factory after receipt of the chip datasheet B:SpringLock D: QuickLock (>200 contacts) P: Thermal drain pad W: Transparent lid H: Open Clamshell Alu (<200 contacts) M: Injection Molded ClamShell I : Steel retention lid J : Clamshell Alu (>200 contacts) R: ReverseLock B: Aluminium retention lid L: Open Lever Clamshell Alu (>200 contacts) T: SlimLock G: Handling button

